ТҮРЕ	V <sub>DSS</sub>	R <sub>DS(on)</sub>	Ι <sub>D</sub>
IRF840	500 V	< 0.85 Ω	8 A

- 100% AVALANCHE TESTED
- NEW HIGH VOLTAGE BENCHMARK
- GATE CHARGE MINIMIZED

### DESCRIPTION

The PowerMESH<sup>TM</sup>II is the evolution of the first generation of MESH OVERLAY<sup>TM</sup>. The layout refinements introduced greatly improve the Ron\*area figure of merit while keeping the device at the leading edge for what concerns switching speed, gate charge and ruggedness.

### **APPLICATIONS**

- HIGH CURRENT, HIGH SPEED SWITCHING
- SWITH MODE POWER SUPPLIES (SMPS)
- DC-AC CONVERTERS FOR WELDING EQUIPMENT AND UNINTERRUPTIBLE POWER SUPPLIES AND MOTOR DR.VE3





Symuol	Parameter	Value	Unit
د VD	Drain-source Voltage (V <sub>GS</sub> = 0)	500	V
VIIGH	Drain-gate Voltage ( $R_{GS}$ = 20 k $\Omega$ )	500	V
VGS	Gate- source Voltage	± 20	V
ID	Drain Current (continuous) at T <sub>C</sub> = 25°C	8	A
ID	Drain Current (continuous) at T <sub>C</sub> = 100°C	5.1	A
I <sub>DM</sub> (•)	Drain Current (pulsed)	32	A
Ртот	Total Dissipation at $T_C = 25^{\circ}C$	125	W
	Derating Factor	1.0	W/°C
dv/dt (1)	Peak Diode Recovery voltage slope	3.5	V/ns
T <sub>stg</sub>	Storage Temperature	–65 to 150	°C
Tj	Max. Operating Junction Temperature	150	°C

#### ABSOLUTE N'A ALAUM RATINGS

(•)Pulse width limited by safe operating area

(1) $I_{SD} \leq 8A$ , di/dt  $\leq 50A/\mu s$ ,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_j \leq T_{JMAX}$ .

# **IRF840**

# THERMAL DATA

Rthj-case	Thermal Resistance Junction-case Max	1	°C/W
Rthj-amb	Thermal Resistance Junction-ambient Max	62.5	°C/W
ΤI	Maximum Lead Temperature For Soldering Purpose	300	°C

# **AVALANCHE CHARACTERISTICS**

Symbol	Parameter	Max Value	Unit
I <sub>AR</sub>	Avalanche Current, Repetitive or Not-Repetitive (pulse width limited by T <sub>j</sub> max)	8	A
E <sub>AS</sub>	Single Pulse Avalanche Energy (starting $T_j = 25 \text{ °C}$ , $I_D = I_{AR}$ , $V_{DD} = 50 \text{ V}$ )	520	mJ

## **ELECTRICAL CHARACTERISTICS** (T<sub>CASE</sub> = 25 °C UNLESS OTHERWISE SPECIFIED) OFF

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>(BR)</sub> DSS	Drain-source Breakdown Voltage	I <sub>D</sub> = 250 μA, V <sub>GS</sub> = 0	500		00	V
IDSS	Zero Gate Voltage Drain Current (V <sub>GS</sub> = 0)	V <sub>DS</sub> = Max Rating V <sub>DS</sub> = Max Rating, T <sub>C</sub> = 125 °C			1 50	μΑ μΑ
IGSS	Gate-body Leakage Current (V <sub>DS</sub> = 0)	V <sub>GS</sub> = ± 20V	ler.	6	±100	nA

# ON (1)

ON (1)		OPS	2	(00	I	
Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>CS</sub> , i <sub>D</sub> = 250µA	2	3	4	V
R <sub>DS(on)</sub>	Static Drain-source On Resistance	$V_{G_{U}} = 10^{\circ}, I_{D} = 3.5 \text{ A}$		0.75	0.85	Ω

## DYNAMIC

Symbol	Paramiter	Test Conditions	Min.	Тур.	Max.	Unit
g <sub>fs</sub> (1)	Forward Transconductance	$V_{DS} > I_{D(on)} \times R_{DS(on)max,}$ $I_{D} = 3.5A$		6.4		S
C <sub>iss</sub>	גיסי.ו Capacitance	$V_{DS} = 25V$ , f = 1 MHz, $V_{GS} = 0$		832		pF
Curs	Output Capacitance			131		pF
Crus	Reverse Transfer Capacitance			17		pF



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### **Source-drain Diode Forward Characteristics**







## Fig. 1: Unclamped Inductive Load Test Circuit



**Fig. 3:** Switching Times Test Circuit For Resistive Load









Fig. 5: Test Circuit For Inductive Load Switching And Diode Recovery Times





# **TO-220 MECHANICAL DATA**

ЫМ		mm.			inch	
DIM.	MIN.	TYP	MAX.	MIN.	TYP.	MAX.
А	4.40		4.60	0.173		0.181
b	0.61		0.88	0.024		0.034
b1	1.15		1.70	0.045		0.066
С	0.49		0.70	0.019		0.027
D	15.25		15.75	0.60		0.620
E	10		10.40	0.393		0.409
е	2.40		2.70	0.094		0.106
e1	4.95		5.15	0.194		0.202
F	1.23		1.32	0.048		0.052
H1	6.20		6.60	0.244		0.256
J1	2.40		2.72	0.094		0.107
L	13		14	0.511		0.551
L1	3.50		3.93	0.137		0.154
L20		16.40			0.645	
L30		28.90			1.137	
øP	3.75		3.85	0.147		0.151
Q	2.65		2.95	0.104		0.116





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